

	<b>Search Text</b>	<b>DBs</b>
1	chip near resistor	US- PGPUB; USPAT; USOCR ; FPRS; EPO; JPO; DERW ENT; IBM_T DB
2	insulation near surface near electrode	US- PGPUB; USPAT; USOCR ; FPRS; EPO; JPO; DERW ENT; IBM_T DB

	<b>Search Text</b>	<b>DBs</b>
<b>3</b>	solder	US- PGPUB; USPAT; USOCR ; FPRS; EPO; JPO; DERW ENT; IBM_T DB
<b>4</b>	1 and 2	US- PGPUB; USPAT
<b>5</b>	1 and 2 and 3	US- PGPUB; USPAT
<b>6</b>	1 and 3	US- PGPUB; USPAT
<b>7</b>	1 and 3 and thick near film	US- PGPUB; USPAT
<b>8</b>	(chip and resistor and insulation and flat and electrodes and solder).clm.	US- PGPUB